

Issue Date: 15 July 2015

Title of Change:	Copper wire conversion and mold compound change for LA72910V/LV72910VL/LA72914V/LA72914VL			
Proposed first ship date:	15 January 2016			
Contact information:	Contact your local ON Semiconductor Sales Office or <ikuo.oosawa@onsemi.com><hidekazu.inoue@onsemi.com> <hiroshi.kojima@onsemi.com> <takeshi2.hoshino@onsemi.com><kazumi.onda@onsemi.com><kenya.iiguchi@onsemi.com></kenya.iiguchi@onsemi.com></kazumi.onda@onsemi.com></takeshi2.hoshino@onsemi.com></hiroshi.kojima@onsemi.com></hidekazu.inoue@onsemi.com></ikuo.oosawa@onsemi.com>			
Samples:	Samples should be available after completion of qualification. Contact your local ON Semiconductor Sales Office or <jun.hasunuma@onsemi.com></jun.hasunuma@onsemi.com>			
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>			
Change Part Identification:	Affected products will be identified with date code.			
Change category:	Wafer Fab Change Assembly Change Test Change Other			
Change Sub-Category(s): <ul> <li>Datasheet/Product Doc change</li> <li>Manufacturing Site Change/Addition</li> <li>Material Change</li> <li>Product specific change</li> <li>Other:</li> </ul>				
Sites Affected:       Image: Site Site Site Site Site Site Site Site				
<ul> <li>Description and Purpose:</li> <li>This is an Initial Process Change Notification for below contents.</li> <li>1) Gold wire connecting chip and Lead will be changed to Copper wire.</li> <li>2) Mold resin will be changed to suitable for Copper wire.</li> <li>There is no change of the electrical characteristic specifications with this changing.</li> </ul>				
Qualification Plan: Estimated date for qualification completion: 31 July 2015 Package name :SSOP016 (225mil)				
Test Items		Test Condition	Test Time	
High Temperature Operating Life		Tj=Tjmax, Vcc=Operatingmax	1000hrs	
Temperature Humidity Bias *		Ta=85degC,RH=85%, Vcc=Recommended T	1000hrs	
Temperature Cycle *		Ta=-65degC(30min) ⇔ Ta=150degC (30min)	100cycles	
Pressure Cooker *		Ta=121degC,RH=100% ,205kPa	50hrs	
High Temperature Storage		Ta=150degC	1000hrs	
Resistance to Soldering heat (Reflow Soldering)		255degC,10s (Peak260degC) 2times		
Notes: The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD				

Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.

Judgment Criteria : Judgment Criteria are due to the limits of the electrical characteristics in the detail specification



List of affected Standard Parts:				
Part Number	Qualification Vehicle			
LA72910V-TLM-H	LA72910VL-TLM-E			
LA72914V-TLM-H				

List of affected Customer Specific Parts:				
Part Number	Qualification Vehicle			
LA72910VL-TLM-E	LA72910VL-TLM-E			
LA72914VL-TLM-H				